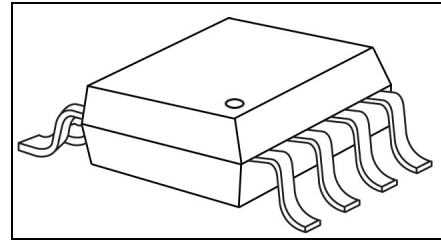




# All-Ways-On™ High-Power LED Driver

## Features

- 2 constant-current output channels
- Constant output current invariant to load voltage change
- Maximum output constant current: 360 mA
- Thermal protection and report
- Output current adjustment
- Schmitt trigger input
- 5V supply voltage
- Package type: “Pb-free & Green” SOP8 with thermal pad



GD: SOP8-150-1.27

| Current Accuracy |             | Conditions   |
|------------------|-------------|--|
| Between Channels | Between ICs |  |
| < ±3%            | < ±6%       | I <sub>OUT</sub> = 40mA ~ 360 mA<br>@ V <sub>DS</sub> = 0.6V |

## Product Description

MBI1802 is an instant On/Off LED driver for high power LED applications and exploits PrecisionDrive™ and All-Ways-On™ technology to enhance its output characteristics.

With All-Ways-On™, MBI1802 easily provides users with a consistent current source in their system design. Users may adjust the output current up to 360 mA through an external resistor, R<sub>ext</sub>, which gives users flexibility in controlling the light intensity of LEDs. Also, users can precisely adjust LED brightness from 0% to 100% via output control with Pulse Width Modulation. Alternatively, MBI1802 provides one-step current adjustment to make a quarter of the output current via enabling the QUAD pin as “High”.

Additionally, to ensure the system reliability, MBI1802 is built with TP (Thermal Protection) function and thermal pad. The TP function can protect IC from over temperature (165°C) and the thermal pad can enhance the power dissipation. As a result, a large amount of current can be handled safely in one package.

## Applications

- High-Flux LED Lighting
- Automotive Interior Lighting

**Typical Application Circuit**

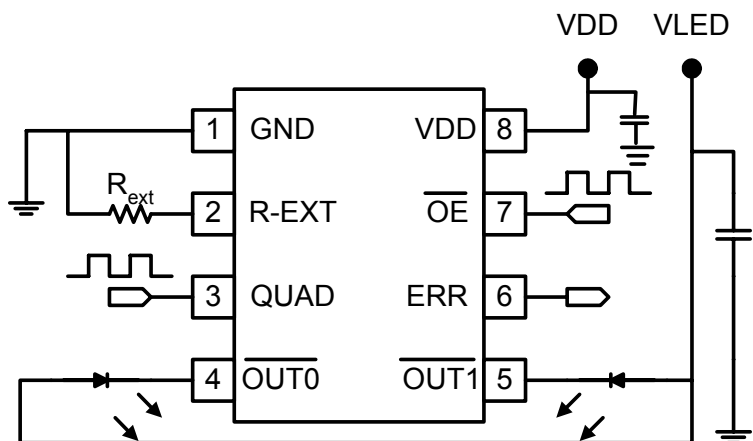
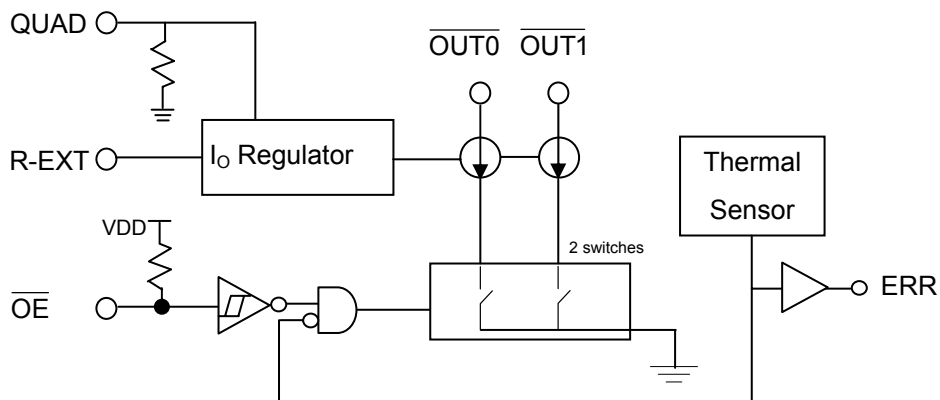
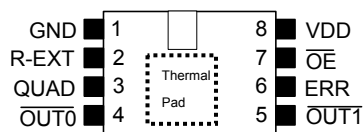


Figure 1

**Block Diagram**



### Pin Configuration



MBI1802GD

### Terminal Description

| Pin No. | Pin Name                               | Function   |
|---------|--|--|
| 1       | GND                                    | Ground terminal for control logic and current sink   |
| 2       | R-EXT                                  | Terminal used to connect an external resistor( $R_{ext}$ ) for setting up output current for all output channels   |
| 3       | QUAD                                   | Set all the output current to 25% of the pre-set current when QUAD is high.  |
| 4, 5    | $\overline{OUT0} \sim \overline{OUT1}$ | Constant current output terminals  |
| 6       | ERR                                    | Thermal error flag, when junction temperature is over 165°C, ERR is going to high.*  |
| 7       | $\overline{OE}$                        | Output enable terminal<br>When $\overline{OE}$ (active) low, the output drivers are enabled; when $\overline{OE}$ high, all output drivers are turned OFF (blanked). |
| 8       | VDD                                    | 5V supply voltage terminal   |
| -       | Thermal Pad                            | Power dissipation terminals with ground connection*  |

\*To eliminate the noise influence, the thermal pad should be connected to GND.

In addition, desired thermal conductivity will be better if the conduction area on PCB connecting to the thermal pad is large enough.

**Maximum Ratings**

| Characteristic                                      |      | Symbol        | Rating               | Unit          |
|---|------|---------------|----------------------|---------------|
| Supply Voltage                                      |      | $V_{DD}$      | 0~7.0                | V             |
| Input Voltage                                       |      | $V_{IN}$      | -0.4~ $V_{DD} + 0.4$ | V             |
| Output Current                                      |      | $I_{OUT}$     | 360*                 | mA            |
| Output Voltage                                      |      | $V_{DS}$      | -0.5~+17.0           | V             |
| GND Terminal Current                                |      | $I_{GND}$     | 720                  | mA            |
| Power Dissipation*<br>(On PCB, $T_a=25^{\circ}C$ )  | SOP8 | $P_D$         | 0.8                  | W             |
| Thermal Resistance*<br>(Under good thermal system)  |      | $R_{th(j-a)}$ | 33.39**              | $^{\circ}C/W$ |
| Thermal Resistance*<br>(On PCB, $T_a=25^{\circ}C$ ) |      |               | 125                  |               |
| Operating Temperature                               |      | $T_{opr}$     | -40~+85              | $^{\circ}C$   |
| Storage Temperature                                 |      | $T_{stg}$     | -55~+150             | $^{\circ}C$   |

\*Users must notice that the power dissipation (almost equaling to  $I_{OUT} \times V_{DS}$ ) should be within the Safe Operation Area shown in Figure 6.

\*\* Good thermal system design can ensure that the heat management of the total system (storage temperature and operating temperature) maintains MBI1802 within the defined temperature limits ( $R_{th(j-a)} = 33.39^{\circ}C/W$ ).

**Electrical Characteristics**

| Characteristic                               |           | Symbol          | Condition  | Min.               | Typ.      | Max.               | Unit       |
|--|-----------|-----------------|--|--------------------|-----------|--------------------|------------|
| Supply Voltage                               |           | $V_{DD}$        | -  | 4.5                | 5.0       | 5.5                | V          |
| Output Voltage                               |           | $V_{DS}$        | $\overline{OUT0} \sim \overline{OUT1}$                                     | -                  | -         | 17.0               | V          |
| Output Current                               |           | $I_{OUT}$       | DC Test Circuit  | 40                 | -         | 360                | mA         |
| Input Voltage                                | “H” level | $V_{IH}$        | $T_a = -40 \sim 85^\circ C$  | $0.7 \cdot V_{DD}$ | -         | $V_{DD}$           | V          |
|  | “L” level | $V_{IL}$        | $T_a = -40 \sim 85^\circ C$  | GND                | -         | $0.3 \cdot V_{DD}$ | V          |
| Output Leakage Current                       |           | $I_{OH}$        | $V_{OH} = 17.0V$   | -                  | -         | 0.5                | $\mu A$    |
| Output Current 1                             |           | $I_{OUT1}$      | $V_{DS} = 0.6V$<br>$R_{ext} = 720 \Omega$                                  | -                  | 204       | -                  | mA         |
| Current Skew                                 |           | $dI_{OUT1}$     | $I_{OL} = 204mA$<br>$V_{DS} = 0.6V$<br>$R_{ext} = 720 \Omega$              | -                  | $\pm 1$   | $\pm 3$            | %          |
| Output Current 2                             |           | $I_{OUT2}$      | $V_{DS} = 0.5V$<br>$R_{ext} = 1440 \Omega$                                 | -                  | 102       | -                  | mA         |
| Current Skew                                 |           | $dI_{OUT2}$     | $I_{OL} = 102mA$<br>$V_{DS} = 0.5V$<br>$R_{ext} = 1440 \Omega$             | -                  | $\pm 1$   | $\pm 3$            | %          |
| Output Current vs. Output Voltage Regulation |           | $\% / dV_{DS}$  | $V_{DS}$ within 1.0V and 3.0V  | -                  | $\pm 0.1$ | -                  | % / V      |
| Output Current vs. Supply Voltage Regulation |           | $\% / dV_{DD}$  | $V_{DD}$ within 4.5V and 5.5V  | -                  | $\pm 1$   | -                  | % / V      |
| Pull-up Resistor                             |           | $R_{IN(up)}$    | $\overline{OE}$  | 250                | 500       | 800                | K $\Omega$ |
| Thermal Protection Temperature               |           | $T_j$           | Junction Temperature   | -                  | 165       | -                  | $^\circ C$ |
| Supply Current                               | “OFF”     | $I_{DD(off) 1}$ | $R_{ext} = \text{Open}, \overline{OUT0} \sim \overline{OUT1} = \text{Off}$ | -                  | 6         | 8                  | mA         |
|  |           | $I_{DD(off) 2}$ | $R_{ext} = 720 \Omega, \overline{OUT0} \sim \overline{OUT1} = \text{Off}$  | -                  | 9         | 11                 |            |
|  |           | $I_{DD(off) 3}$ | $R_{ext} = 230 \Omega, \overline{OUT0} \sim \overline{OUT1} = \text{Off}$  | -                  | 15        | 17                 |            |
|  | “ON”      | $I_{DD(on) 1}$  | $R_{ext} = 720 \Omega, \overline{OUT0} \sim \overline{OUT1} = \text{On}$   | -                  | 5         | 7                  |            |
|  |           | $I_{DD(on) 2}$  | $R_{ext} = 230 \Omega, \overline{OUT0} \sim \overline{OUT1} = \text{On}$   | -                  | 11        | 13                 |            |

**Test Circuit for Electrical Characteristics**

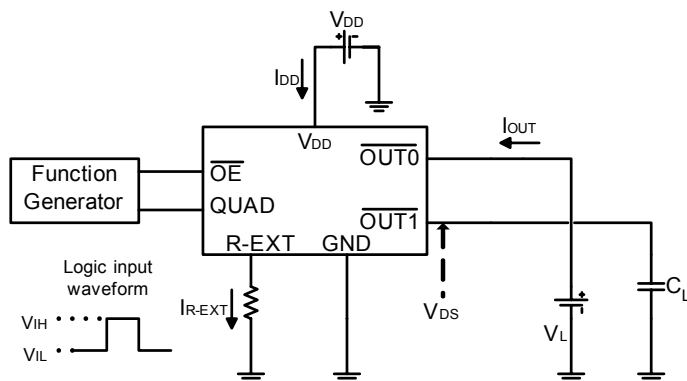


Figure 2

**Switching Characteristics**

| Characteristic                      | Symbol                            | Condition   | Min.        | Typ. | Max. | Unit          |               |
|-------------------------------------|-----------------------------------|---|-------------|------|------|---------------|---------------|
| Propagation Delay Time ("L" to "H") | $\overline{OE} - \overline{OUTn}$ | $V_{DD} = 5.0\text{ V}$<br>$V_{DS} = 1-1.6\text{ V}$<br>$V_{IH} = V_{DD}$<br>$V_{IL} = \text{GND}$<br>$R_{ext} = 600\ \Omega$<br>$V_L = 4.0\text{ V}$<br>$R_L = 10\ \Omega$<br>$C_L = 10\text{ pF}$ | 1           | 2    | 3    | $\mu\text{s}$ |               |
| Propagation Delay Time ("H" to "L") | $\overline{OE} - \overline{OUTn}$ |   | $t_{pHL}$   | 1    | 2    | 3             | $\mu\text{s}$ |
| Pulse Width                         | $\overline{OE}$                   |   | $t_{w(OE)}$ | 10   | -    | -             | $\mu\text{s}$ |
| Output Rise Time of Vout (turn off) |                                   |   | $t_{or}$    | 1    | 1.7  | 3             | $\mu\text{s}$ |
| Output Fall Time of Vout (turn on)  |                                   |   | $t_{of}$    | 1    | 1.7  | 3             | $\mu\text{s}$ |

**Test Circuit for Switching Characteristics**

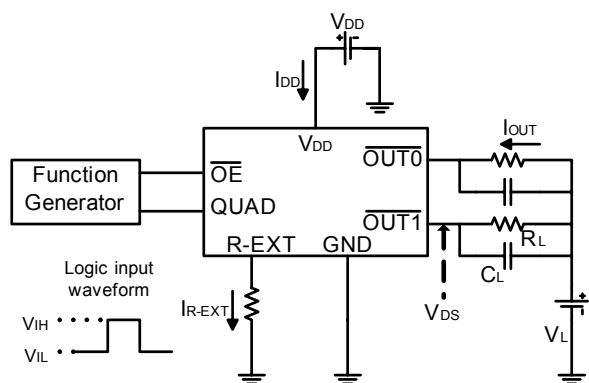


Figure 3

### Application Information

#### Constant Current

In LED lighting applications, MBI1802 provides nearly no variations in current from channel to channel and from IC to IC. This can be achieved by:

- 1) The maximum current variation between channels is less than ±3%, and that between ICs is less than ±6%.
- 2) In addition, the current characteristic of output stage is flat and users can refer to the figure as shown below. The output current can be kept constant regardless of the variations of LED forward voltages ( $V_F$ ). This performs as a perfection of load regulation.

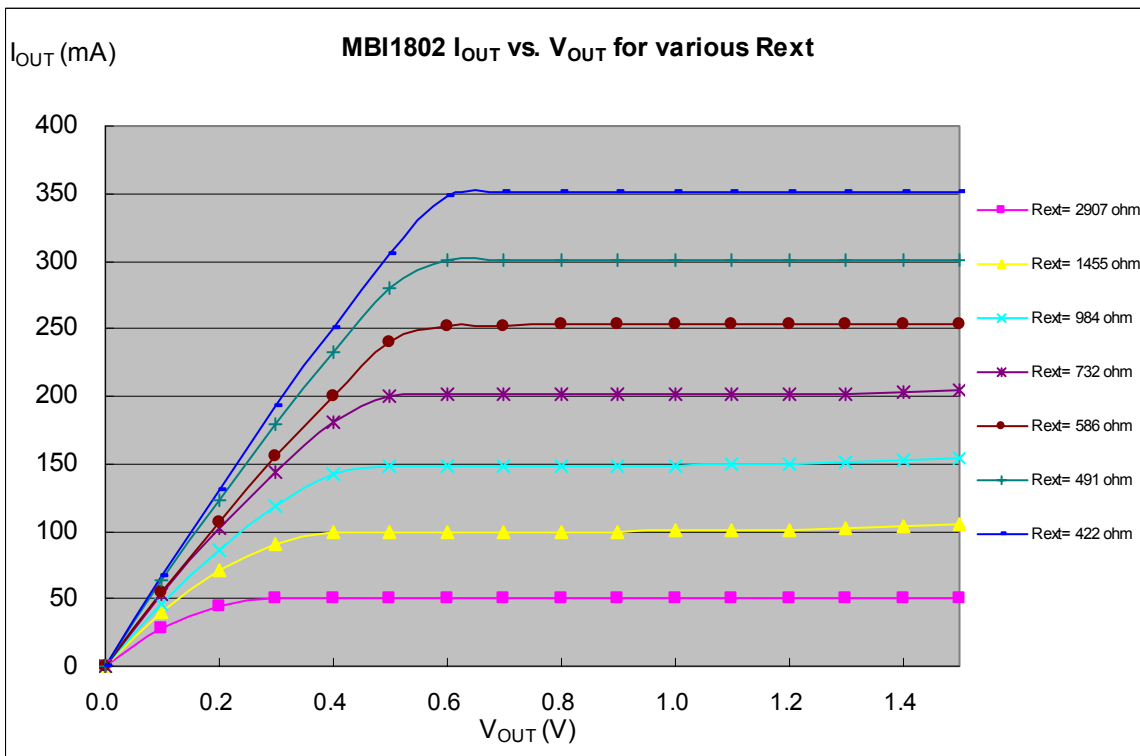


Figure 4

### Adjusting Output Current

The output current of each channel ( $I_{OUT}$ ) is set by an external resistor,  $R_{ext}$ . The relationship between  $I_{OUT}$  and  $R_{ext}$  is shown in the following figure.

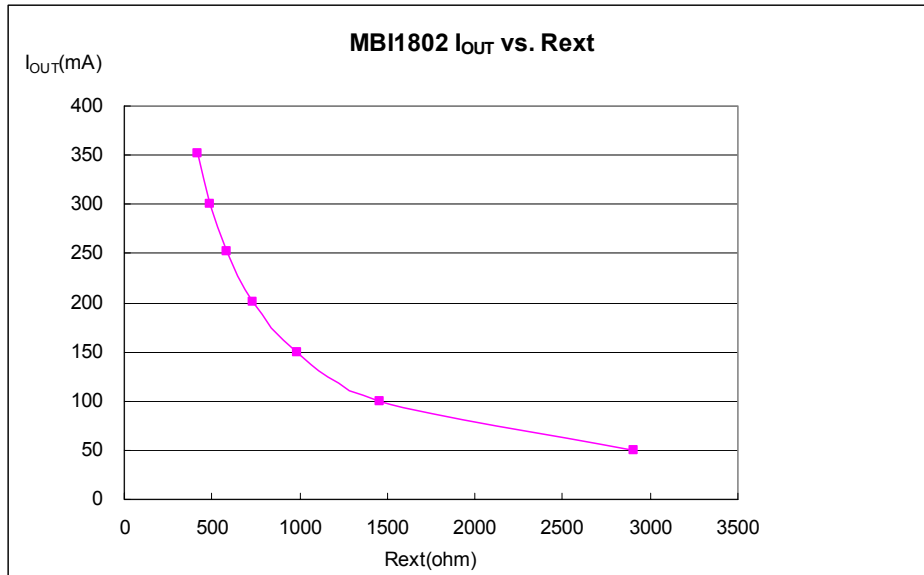


Figure 5

Also, the output current can be calculated from the equation:

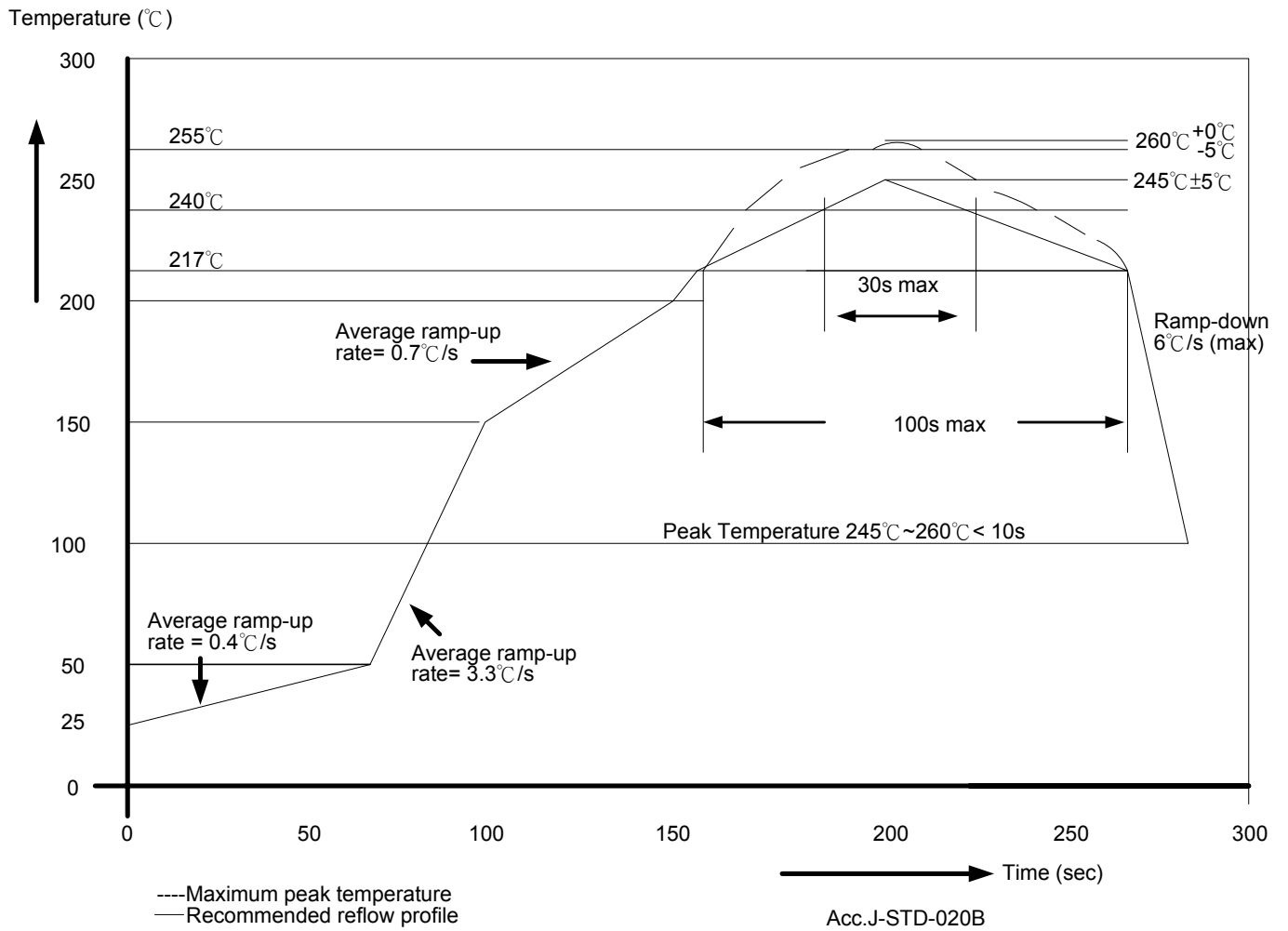
$$V_{R-EXT} = 1.28V ; R_{ext} = (V_{R-EXT} / I_{OUT}) \times 115 = (1.28V / I_{OUT}) \times 115$$

where  $R_{ext}$  is the resistance of the external resistor connected to R-EXT terminal and  $V_{R-EXT}$  is the voltage of R-EXT terminal. The magnitude of current (as a function of  $R_{ext}$ ) is around 102 mA at 1440Ω and 204 mA at 720Ω.



**Soldering Process of “Pb-free & Green” Package Plating\***

Macroblock has defines "Pb-Free & Green" to mean semiconductor products that are compatible with the current RoHS requirements and selected **100% pure tin (Sn)** to provide forward and backward compatibility with both the current industry-standard SnPb-based soldering processes and higher-temperature Pb-free processes. Pure tin is widely accepted by customers and suppliers of electronic devices in Europe, Asia and the US as the lead-free surface finish of choice to replace tin-lead. Also, it is backward compatible to standard 215°C to 240°C reflow processes which adopt tin/lead (SnPb) solder paste. However, in the whole Pb-free soldering processes and materials, 100% pure tin (Sn), will all require up to 260°C for proper soldering on boards, referring to J-STD-020B as shown below.



\*Note1: For details, please refer to Macroblock’s “Policy on Pb-free & Green Package”.

### Package Power Dissipation (P<sub>D</sub>)

The maximum power dissipation,  $P_D(max) = (T_j - T_a) / R_{th(j-a)}$ , decreases as the ambient temperature increases.

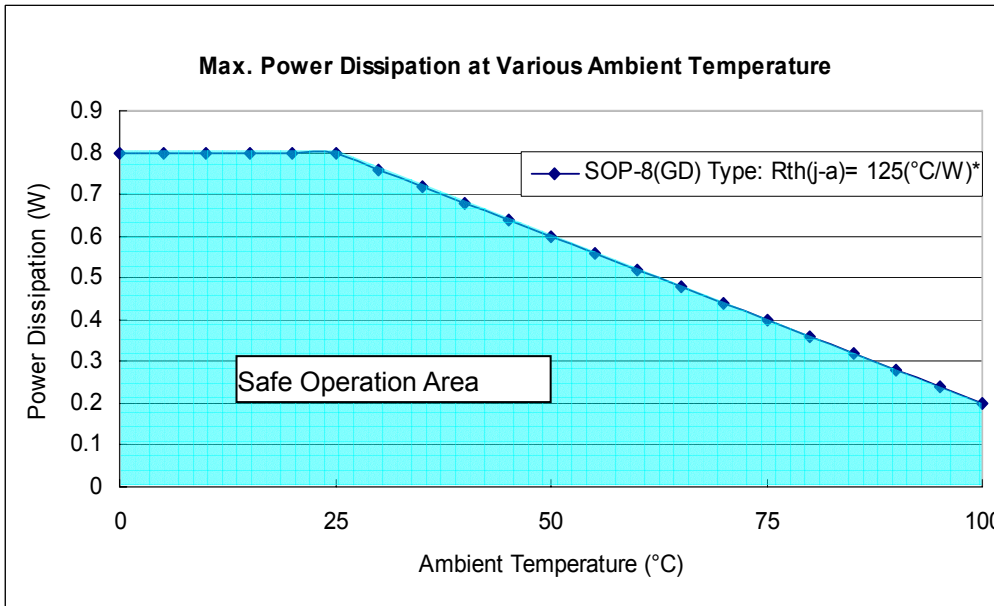


Figure 6

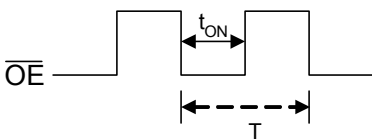
The maximum allowable package power dissipation is determined as  $P_D(max) = (T_j - T_a) / R_{th(j-a)}$ . When 2 output channels are turned on simultaneously, the actual package power dissipation is  $P_D(act) = (I_{DD} \times V_{DD}) + (I_{OUT} \times Duty \times V_{DS} \times 2)$ . Therefore, to keep  $P_D(act) \leq P_D(max)$ , the allowable maximum output current as a function of duty cycle is:

$$I_{OUT} = \{ [(T_j - T_a) / R_{th(j-a)}] - (I_{DD} \times V_{DD}) \} / V_{DS} / Duty / 2,$$

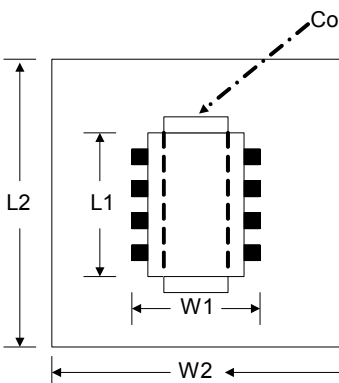
where  $T_j = 125^\circ\text{C}$ ;

$$Duty = t_{ON} / T;$$

$t_{ON}$ : the time of LEDs turning on;  $T$ :  $\overline{OE}$  signal period



\*Note1: The thermal resistor  $R_{th(j-a)} = 125^\circ\text{C/W}$  is based on the following structure.



The PCB area  $L2 \times W2$  is 4 times to the IC's area  $L1 \times W1$ .

The thickness of the PCB is 1.6mm, copper foil 1 Oz. The thermal pad on the IC's bottom has to be mounted on the copper foil.

**TP Function (Thermal Protection)**

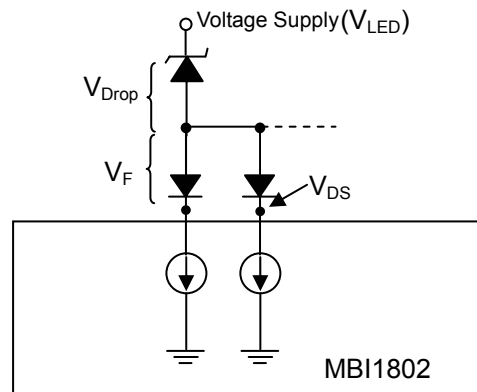
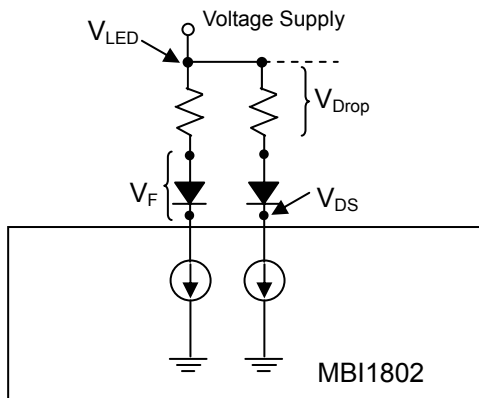
When the junction temperature exceeds the limit (165°C), TP starts to function and turn off the output current and the thermal error flag, ERR, goes high simultaneously. As soon as the temperature is below 165°C, the output current will be on again. The switching runs at a high frequency, so the blinking is imperceptible. However, the DC output current is limited and thus the driver is protected from overheat.

**Load Supply Voltage (V<sub>LED</sub>)**

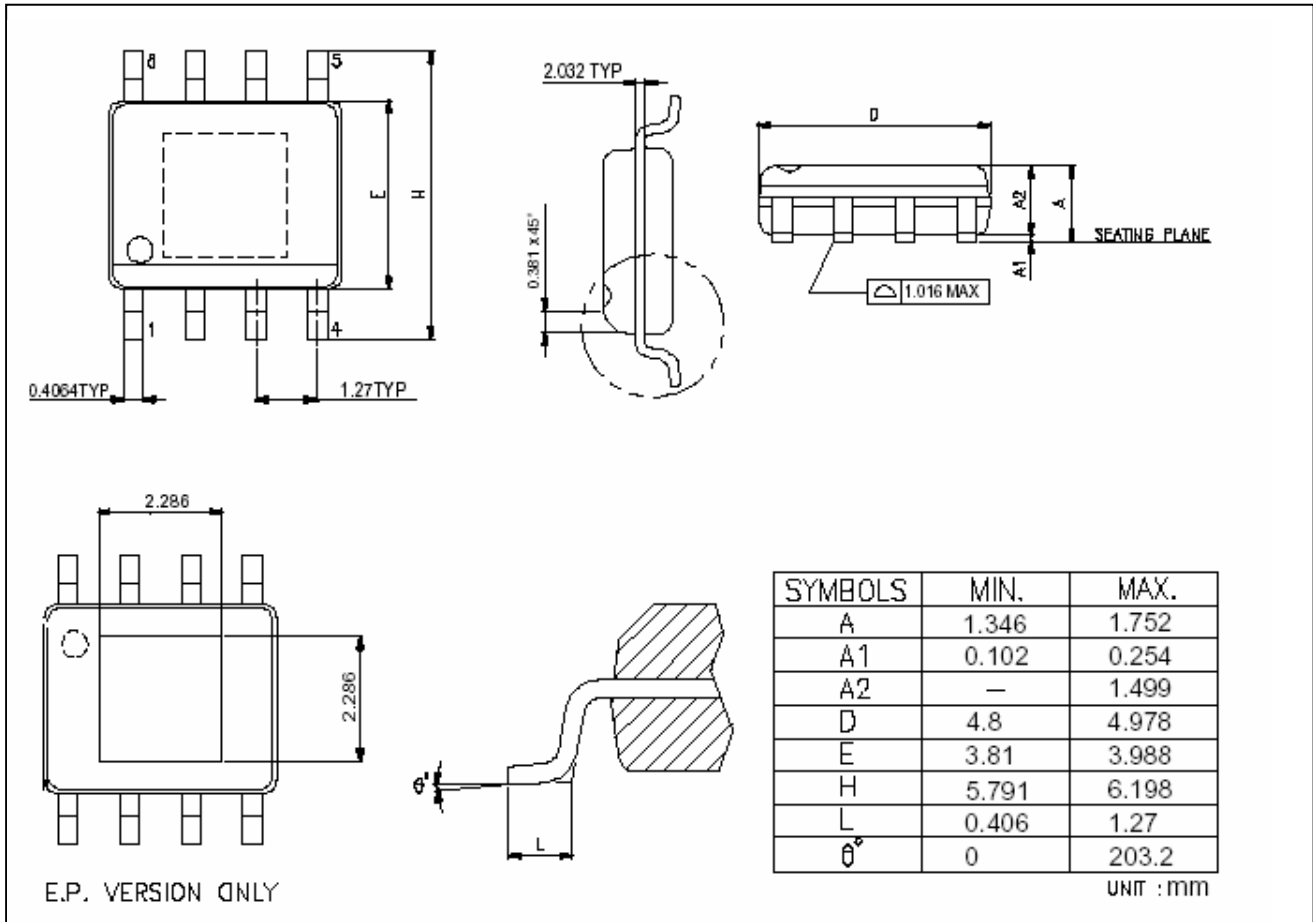
MBI1802 are designed to operate with V<sub>DS</sub> ranging from 0.4V to 1.0V considering the package power dissipating limits. V<sub>DS</sub> may be higher enough to make P<sub>D(act)</sub> > P<sub>D(max)</sub> when V<sub>LED</sub> = 5V and V<sub>DS</sub> = V<sub>LED</sub> - V<sub>F</sub>, in which V<sub>LED</sub> is the load supply voltage. In this case, it is recommended to use the lowest possible supply voltage or to set an external voltage reducer, V<sub>DROP</sub>.

A voltage reducer lets V<sub>DS</sub> = (V<sub>LED</sub> - V<sub>F</sub>) - V<sub>DROP</sub>.

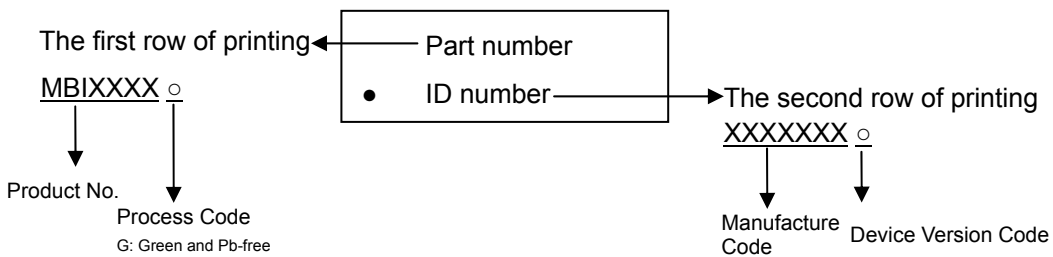
Resistors or Zener diode can be used in the applications as shown in the following figures.



**Outline Drawing**



**Product Top-mark Information**



**Product Revision History**

| Datasheet version | Device version code |
|-------------------|---------------------|
| V1.00             | Not defined         |
| V1.01             | A                   |

**Product Ordering Information**

| Part Number | Package Type  | Weight (g) |
|-------------|---------------|------------|
| MBI1802     | SOP8-150-1.27 | 0.07       |